

# Global Underfill for IC Packaging Market Growth 2024-2030

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## Abstracts

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Underfill adhesive for IC packaging is a high-fluidity, high-filling capacity adhesive material specially used in the semiconductor chip packaging process. Its main function is to form a filling layer between the chip and the substrate to enhance the mechanical strength, thermal stability and electrical performance of the chip package.

The global Underfill for IC Packaging market size is projected to grow from US\$ 390 million in 2024 to US\$ 567 million in 2030; it is expected to grow at a CAGR of 6.4% from 2024 to 2030.

LP Information, Inc. (LPI) ' newest research report, the “Underfill for IC Packaging Industry Forecast” looks at past sales and reviews total world Underfill for IC Packaging sales in 2023, providing a comprehensive analysis by region and market sector of projected Underfill for IC Packaging sales for 2024 through 2030. With Underfill for IC Packaging sales broken down by region, market sector and sub-sector, this report provides a detailed analysis in US\$ millions of the world Underfill for IC Packaging industry.

This Insight Report provides a comprehensive analysis of the global Underfill for IC Packaging landscape and highlights key trends related to product segmentation, company formation, revenue, and market share, latest development, and M&A activity. This report also analyzes the strategies of leading global companies with a focus on Underfill for IC Packaging portfolios and capabilities, market entry strategies, market positions, and geographic footprints, to better understand these firms' unique position in an accelerating global Underfill for IC Packaging market.

This Insight Report evaluates the key market trends, drivers, and affecting factors shaping the global outlook for Underfill for IC Packaging and breaks down the forecast by Type, by Application, geography, and market size to highlight emerging pockets of opportunity. With a transparent methodology based on hundreds of bottom-up qualitative and quantitative market inputs, this study forecast offers a highly nuanced view of the current state and future trajectory in the global Underfill for IC Packaging.

United States market for Underfill for IC Packaging is estimated to increase from US\$ million in 2023 to US\$ million by 2030, at a CAGR of % from 2024 through 2030.

China market for Underfill for IC Packaging is estimated to increase from US\$ million in 2023 to US\$ million by 2030, at a CAGR of % from 2024 through 2030.

Europe market for Underfill for IC Packaging is estimated to increase from US\$ million in 2023 to US\$ million by 2030, at a CAGR of % from 2024 through 2030.

Global key Underfill for IC Packaging players cover Henkel, Won Chemical, NAMICS, Resonac, Panasonic, etc. In terms of revenue, the global two largest companies occupied for a share nearly

% in 2023.

This report presents a comprehensive overview, market shares, and growth opportunities of Underfill for IC Packaging market by product type, application, key manufacturers and key regions and countries.

Segmentation by Type:

FC Underfill

BGA Underfill

WLCSP Underfill

Segmentation by Application:

Smart Phone

Tablets & Laptops

Automotive Electronics

Others

This report also splits the market by region:

Americas

United States

Canada

Mexico

Brazil

APAC

China

Japan

Korea

Southeast Asia

India

Australia

Europe

Germany

France

UK

Italy

Russia

Middle East & Africa

Egypt

South Africa

Israel

Turkey

GCC Countries

The below companies that are profiled have been selected based on inputs gathered from primary experts and analysing the company's coverage, product portfolio, its market penetration.

Henkel

Won Chemical

NAMICS

Resonac

Panasonic

MacDermid Alpha

Shin-Etsu

Sunstar

Fuji Chemical

Zymet

Shenzhen Dover

Threebond

AIM Solder

Darbond

Master Bond

Hanstars

Nagase ChemteX

LORD Corporation

Asec Co., Ltd.

Everwide Chemical

Bondline

Panacol-Elosol

United Adhesives

U-Bond

Shenzhen Coateck Electronic Material Technology

## Key Questions Addressed in this Report

What is the 10-year outlook for the global Underfill for IC Packaging market?

What factors are driving Underfill for IC Packaging market growth, globally and by region?

Which technologies are poised for the fastest growth by market and region?

How do Underfill for IC Packaging market opportunities vary by end market size?

How does Underfill for IC Packaging break out by Type, by Application?

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